8-bit Proprietary Microcontroller

CMOS

F²MC-8L MB89960 Series

MB89965/P965A/F969A/ MB89PV960

■ DESCRIPTION

The MB89960 series is a single-chip microcontroller that utilizes the F²MC-8L core for low voltage and high speed performance. The microcontroller contains a range of peripheral functions including timers, a serial interface, I²C interface, A/D converter, and external interrupts. The internal I²C interface complies with the SM bus standard and supports an SM bus battery controller.

■ FEATURES

- Range of package options
- QFP and MQFP packages (0.8 mm pitch)
- LQFP package (0.5 mm and 0.65 mm pitch)
- · High speed operation at low voltage

Minimum instruction execution time = $0.4 \mu s$ (for a 10 MHz oscillation)

• F2MC-8L CPU core

Instruction set optimized for controller applications

- · Multiplication and division instructions
- 16-bit arithmetic operations
- · Bit test branch instructions
- Bit manipulation instructions, etc.

· Dual-clock control system

• Main clock: 10 MHz max.

(Four speed settings available, oscillation halts in sub-clock mode)

• Sub-clock: 32.768 kHz (Operation clock for sub-clock mode)

Four channels

- 8/16-bit timer/counter (8-bit × 2 channels or 16-bit × 1 channel)
- · 21-bit timebase timer
- Clock prescaler (15-bit)

Serial I/O

Selectable transfer format (MSB-first or LSB-first) supports communications with a wide range of devices.

A/D converter

10-bit × 4 channels

External interrupts

- External interrupt 1 (3 channels)
 - Three independent interrupt inputs can be used to recover from low-power consumption modes (with edge-detection function)
- External interrupt 2 (1 channel with 8 inputs)
 Eight inputs can be used to recover from low-power consumption modes (with "L" level detection function)
- Low-power consumption modes (standby modes)
- Stop mode (As all oscillations halt in sub-clock mode, current consumption falls to almost zero.)
- Sleep mode (The CPU stops to reduce the current consumption to approximately 1/3 of normal.)
- Clock mode (All operation halts other than the clock prescaler resulting in very low power consumption.)

• I2C interface*

- Supports Intel SM bus and Philips I²C bus standards.
- Uses a two-wire data transfer protocol.

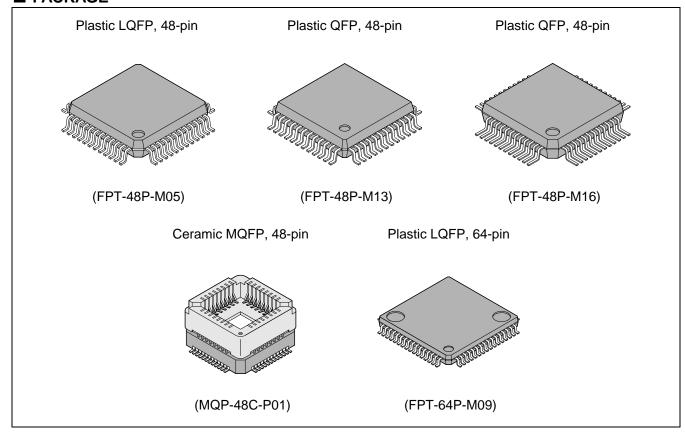
• Max. 35 I/O ports

Output-only ports (N-ch open drain) : 6
General-purpose I/O ports (CMOS) : 21
Output-only ports (CMOS) : 8

*: I2C license

The customer is licensed to use the Philips I²C patent when using this product in an I²C system that complies with the Philips I²C standard specifications.

■ PACKAGE



■ PRODUCT LINEUP

	Part No.	MB89965	MB89P965A	MB89F969A	MB89PV960		
Pram	eter	Mass-produced			Piggyback/		
Classification		products (mask ROM products)	One-time product	Flash product	evaluation product for testing and development		
ROM	size	16 K × 8-bit (Interr	nal mask ROM)	60 K × 8-bit	32 K × 8-bit (External ROM) *		
RAM	size	512×8	3-bit	1024	× 8-bit		
Number of instructions : 136 Instruction bit length : 8-bit Instruction length : 1 to 3 bytes Data bit length : 1-, 8-, 16bits Minimum execution time : 0.4 μs (at 10 MHz) Interrupt processing time : 3.6 μs (at 10 MHz)							
	Ports	Output-only ports (CMC General-purpose I/O po Total	Output-only ports (N-ch open drain) : 6 (4 pins are shared (2 pins are shared : 8 Output-only ports (CMOS) : 8 General-purpose I/O ports (CMOS) : 21 (shared with resolute) Total : 35 (max.)				
	Timebase timer	21-bit Four interrupt intervals selectable 0.82 ms, 3.3 ms, 26.2 ms, or 419.4 ms (approx.) (t main clock)					
	Watchdog timer	Reset trigger period : 419.4 ms (10 MHz main clock) 500 ms (32.768 MHz sub-clock)					
		One channel. Supports Uses a 2-wire protocol f			ous standards.		
Pe- riph- eral	I ² C interface	Included/Not included (Specified when order- ing. See "Ordering In- formation" for details.)		Included			
functions 8/16-bit timer/ counter Timer 2 channel 8-bit timer/counter operation (independent optimer 2) or 16-bit timer/counter operation (operation clock can execute an event counter operation and output a solution clock. 1 or 16-bit timer/counter operation mode				eration clock period :	0.8 μs to 204.8 μs)		
	Serial I/O	8 bits LSB-first or MSB-first selectable Transfer clocks: External or three internal clocks (0.8 μs, 3.2 μs, 12.8 μs)					
External interrupt 1 (edge) Selectable edge detection (rising, falling, or either edge) 3 independent channels These can also be used to recover from standby modes (ein stop mode).				- ,	ection is still available		
	External 1 channel with 8 inputs ("L" level interrupts, independent input enable) interrupt 2 This can also be used to recover from standby modes (level detection is stop mode).						

(Continued)

(OO/111)	7 2 4 4						
Part No.		MB89965	MB89P965A	MB89F969A	MB89PV960		
Pe- riph- eral func- tions	A/D converter	4 channel × 10-bit resolution A/D conversion time: 15.2 μs (MB89965, MB89P965A, MB89F969A) 13.2 μs (MB89PV960) Continuous activation is available using the output from the 8/16-bit timer/counter timebase timer. Reference voltage input (AVR)					
Clock prescaler 15-bit Interrupt interval : 31.25 ms, 0.25 s, 0.50 s, 1.00 s (for a 32.768 kHz sub-					łz sub-clock)		
Low power consumption (standby modes) Sleep mode, stop mode, and clock mode							
Process		CMOS					
Opera	ating voltage	3.5 V to 5.5 V					

^{*:} Use the MBM27C256A-20TVM as the external ROM (Operating voltage: 4.5 V to 5.5 V)

Note: Unless otherwise stated, clock periods and conversion times are for 10 MHz operation with the main clock operating at maximum speed.

■ PACKAGES AND CORRESPONDING PRODUCTS

Part No. Package	MB89965	MB89P965A	MB89F969A	MB89PV960
FPT-48P-M05	0	0	×	×
FPT-48P-M13	0	0	×	×
FPT-48P-M16	0	0	×	×
FPT-64P-M09	×	×	0	×
MQP-48C-P01	×	×	×	0

: Available× : Not available

■ DIFFERENCES AMONG PRODUCTS

1. Memory Space

Please take note of the differences among products before testing and developing software for the MB89960 series.

- The RAM and ROM configurations differ among products.
- If the bottom stack address is set at the top RAM address, this will need to be relocated if changing to a different product.

2. Current Consumption

- In the case of the MB89PV960, add the current consumed by the EPROM which is connected to the top socket.
- When operated at low speed, one-time PROM and EPROM products will consume more current than mask ROM products. However, the current consumption in sleep/stop modes is the same.

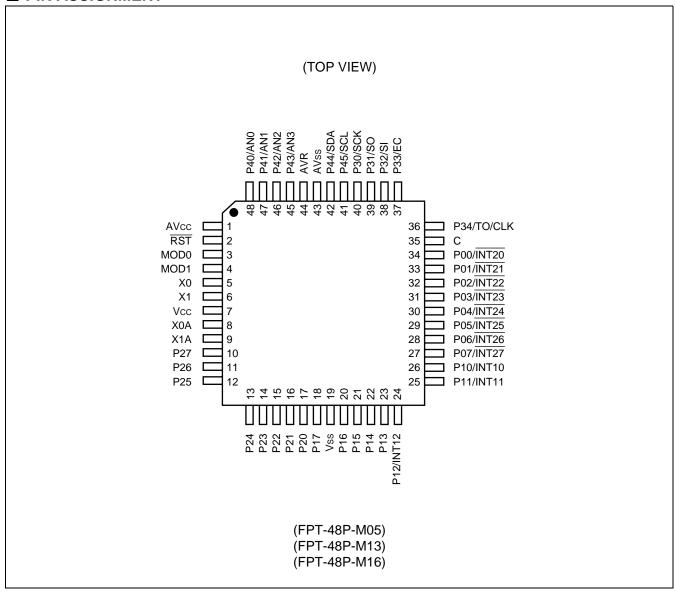
3. Functional Differences Between MB89960 Series

	MB89965/P965A/F969A	MB89PV960
Power-on reset delay time	Regulator stabilization delay time, regulator recovery time, oscillation stabilization delay time	Oscillation stabilization delay time
External reset delay time in stop/ sub-clock mode or external interrupt delay time in main stop mode	Regulator recovery time, oscillation stabilization delay time	Oscillation stabilization delay time
Port pin pull-up resistors	Software-selectable	Not available
A/D conversion time	38 instruction cycles	33 instruction cycles
I ² C noise elimination circuit	Always present regardless of ICCR : DMPB bit setting	Disabled if ICCR : DMPB bit = "1"

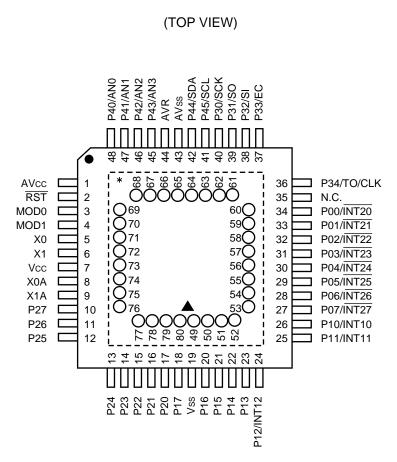
4. Mask Options

Functions that can be selected as options and the methods used to specify these options vary by the product. Before using mask options, check section " Mask Options".

■ PIN ASSIGNMENT



(Continued)

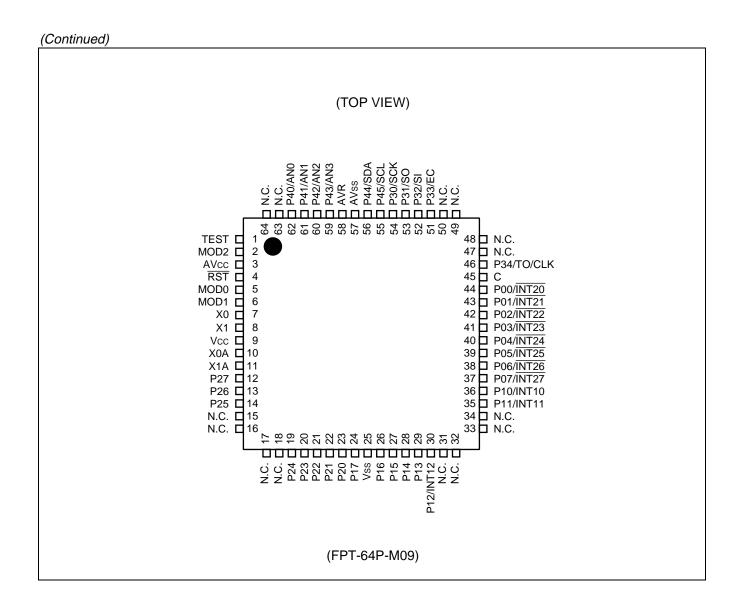


(MQP-48C-P01)

* : Pin assignment on package top (MB89PV960)

Pin No.	Pin Name	Pin No.	Pin Name	Pin No.	Pin Name	Pin No.	Pin Name
49	V _{PP}	57	N.C.	65	O4	73	ŌĒ
50	A12	58	A2	66	O5	74	N.C.
51	A7	59	A1	67	O6	75	A11
52	A6	60	A0	68	07	76	A9
53	A5	61	O1	69	O8	77	A8
54	A4	62	O2	70	CE	78	A13
55	А3	63	О3	71	A10	79	A14
56	N.C.	64	Vss	72	N.C.	80	Vcc

N.C.: Internally connected. Do not use.



■ PIN DESCRIPTIONS

Pin No.		Oine.	Oimessit.		
MQFP-48*3	LQFP-48*1 QFP-48*2	LQFP-64*4	Pin Name	Circuit Type	Function
5	5	7	X0		Oscillator connection pins for the main clock os-
6	6	8	X1	А	cillator (crystal oscillator or similar) . When using an external clock, input the clock signal to X0 and leave X1 open.
8	8	10	X0A		Oscillator connection pins for the sub-clock os-
9	9	11	X1A	В	cillator (crystal oscillator or similar). When using an external clock (low speed: 32.768 kHz), input the clock signal to X0A and leave X1A open.
3	3	5	MOD0	С	Input pins for setting the memory access mode.
4	4	6	MOD1		Connect directly to Vss.
2	2	4	RST	D	Reset I/O pin This is an N-ch open-drain output type with pull- up resistor and a hysteresis input type. The pin outputs "L" when an internal reset is present. Similarly, inputting "L" initializes the internal cir- cuits.
27 to 34	27 to 34	37 to 44	P00/INT20 to P07/INT27	E	General-purpose I/O ports Also serves as the external interrupt 2 inputs (wakeup inputs) . The external interrupt 2 inputs are hysteresis inputs.
24 to 26	24 to 26	30, 35, 36	P10/INT10 to P12/INT12	E	General-purpose I/O ports Also serves as the external interrupt 1 inputs (wakeup inputs) . The external interrupt 1 inputs are hysteresis inputs.
18, 20 to 23	18, 20 to 23	24, 26 to 29	P13 to P17	E	General-purpose I/O ports
10 to 17	10 to 17	12 to 14 19 to 23	P20 to P27	G	General-purpose outoput-only ports
40	40	54	P30/SCK	F	General-purpose I/O port Also serves as the serial clock I/O. A hysteresis input.
39	39	53	P31/SO	F	General-purpose I/O port Also serves as the serial I/O data output. A hysteresis input.

*1 : FPT-48P-M05 (Continued)

*2 : FPT-48P-M16, FPT-48P-M13

*3 : MQP-48C-P01 *4 : FPT-64P-M09

•	Pin No.			Oimessit.	
MQFP-48*3	LQFP-48*1 QFP-48*2	LQFP-64*4	Pin Name	Circuit Type	Function
38	38	52	P32/SI	F	General-purpose I/O port Also serves as the serial I/O data input. A hysteresis input.
37	37	51	P33/EC	F	General-purpose I/O port Also serves as the external clock input for the 8/ 16-bit timer/counter. A hysteresis input.
36	36	46	P34/TO/ CLK	F	General-purpose I/O port Also serves as the overflow output for the 8/16- bit timer/counter and the CLK clock output. A hysteresis input.
_	35	45	С		Connect a 0.1 μF capacitor on the MB89965, MB89P965A, and MB89F969A.
45 to 48	45 to 48	59 to 62	P40/AN0 to P43/AN3	Н	General-purpose Nch open-drain outputs. Also serves as the A/D converter analog inputs.
42	42	56	P44/SDA	I	General-purpose Nch open-drain output. Also serves as the I ² C interface data output.
41	41	55	P45/SCL	I	General-purpose Nch open-drain output. Also serves as the I ² C interface clock I/O.
7	7	9	Vcc		Power supply pin
19	19	25	Vss		Power supply (GND) pin
1	1	3	AVcc	_	A/D converter power supply pin Use this pin at the same voltage as Vcc.
44	44	58	AVR		A/D converter reference voltage input pin
43	43	57	AVss	_	A/D converter power supply pin Use this pin at the same voltage as Vss.
35	_	15 to 18 31 to 34 47 to 50 63, 64	N.C.	_	These pins are not connected. Do not connect these on the MB89PV960.
_	_	1	TEST	С	TEST pin. Connect directly to Vss. Only used on the MB89F969A. Treat as an N.C. pin on the MB89965.
_		2	MOD2	С	Memory access mode setting pin. Connect directly to Vss. Only used on the MB89F969A. Treat as an N.C. pin on the MB89965.

^{*1:} FPT-48P-M05

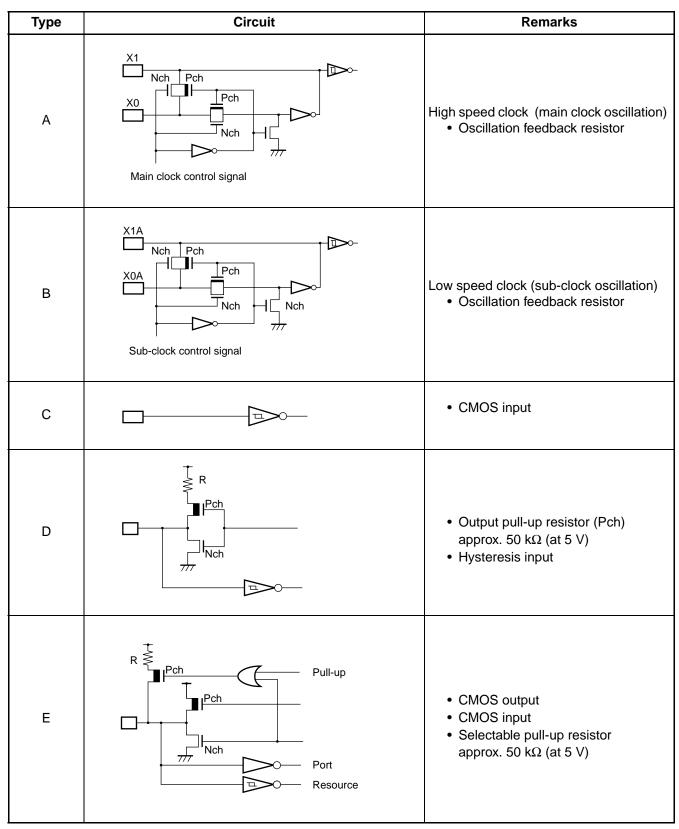
^{*2:} FPT-48P-M16, FPT-48P-M13

^{*3 :} MQP-48C-P01 *4 : FPT-64P-M09

• Pin Descriptions for External EPROM (MB89PV960 only)

Pin No.	Pin Name	I/O	Function
49	Vpp	0	"H" level output pin
50 51 52 53 54 55	A12 A7 A6 A5 A4 A3	0	Address output pins
58 59 60	A2 A1 A0	0	Address output pins
61 62 63	O1 O2 O3	I	Data input pins
64	Vss	_	Power supply (GND) pin
65 66 67 68 69	O4 O5 O6 O7 O8	I	Data input pins
70	CE	0	ROM chip enable pin Outputs "H" during standby mode.
71	A10	0	Address output pin
73	ŌĒ	0	ROM output enable pin Always outputs "L".
75 76 77 78 79	A11 A9 A8 A13 A14	0	Address output pins
80	Vcc	_	EPROM power supply pin
56 57 72 74	N.C.	_	Internally connected pins Always leave open circuit.

■ I/O CIRCUIT TYPE



(Continued) Type	Circuit	Remarks
F	Pull-up Pch Nch Resource	 CMOS output Hysteresis input Selectable pull-up resistor approx. 50 kΩ (at 5 V)
G	Pch Nch	CMOS output
Н	Pull-up Nch Analog input	 Nch-open drain output Analog input (A/D converter) Selectable pull-up resistor (The pull-up resistor cannot be used when used as an analog input.) approx. 50 kΩ (at 5 V)
I	Nch SMB buffer SMB input I ² C buffer I ² C input	 Nch open drain output Selectable SMB or I²C input buffer

HANDLING DEVICES

1. Do not exceed maximum rated voltage (to prevent latch-up)

Latch-up may occur on CMOS ICs if voltage higher than Vcc or lower than Vss is applied to input or output pins other than medium- and high voltage pins or if the voltage applied between Vcc and Vss higher the rating. If latch-up occurs, the power supply current increases rapidly resulting in thermal damage to circuit elements. Therefore, ensure that maximum ratings are not exceeded in circuit operation.

Similarly, when turning the analog power supply on or off, ensure the analog power supply voltages (AV $_{CC}$ and AVR) and analog input voltages do not exceed the digital power supply (V $_{CC}$).

2. Power supply voltage fluctuations

Rapid fluctuation of the voltage may cause the device to misoperate, even if the voltage remains within the allowed operating range.

The standard for power supply voltage stability is a peak-to-peak Vcc ripple voltage at the mains supply frequency (50 to 60 Hz) of 10% or less of Vcc and a transient voltage change rate of 0.1 V/ms or less such as when turning the power supply on or off.

3. Treatment of unused input pins

Leaving unused input pins unconnected can cause misoperation or permanent damage to the device due to latchup. Always pull-up or pull-down unused input pins using a 2 k Ω or larger resistor.

If some I/O pins are unused, either set as outputs and leave open circuit or set as inputs and treat in the same way as input pins.

4. Treatment of N.C. pins

Always leave N.C. (internally connected) pins open.

5. Treatment of power supply pins on microcontrollers with an A/D converter

Even if not using the A/D converter, connect to be AVcc = Vcc and AVss = AVR = Vss.

6. Precautions on using an external clock

An oscillation stabilization delay occurs after a power-on reset or when recovering from sub-clock or stop mode, even if an external clock is used.

■ PROGRAMMING SPECIFICATIONS FOR ONE-TIME PROM PRODUCTS

The MB89P965A has a "PROM mode" that enables the microcontroller to be programmed using a general-purpose ROM programmer via a special adaptor. Note, however, that electronic signature mode is not available.

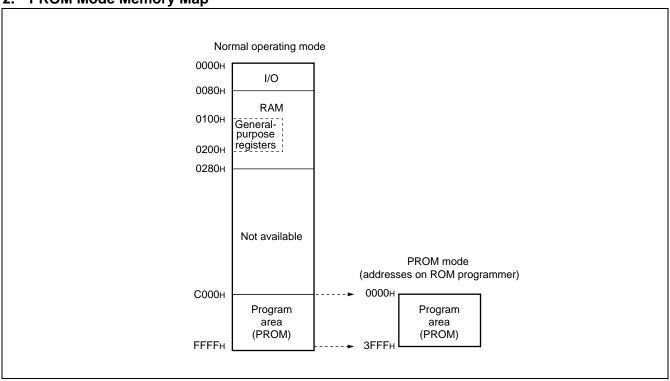
1. ROM Programmer Adaptor and Recommended ROM Writers

Package Name	Adaptor Part No.	Recommended Programmer Manufacturer and Model
rackage Name	Sun Hayato Co. Ltd.	Ando Denki Co. Ltd.
FPT-48P-M05	ROM2-48LQF-32DP-8LA	
FPT-48P-M13	ROM2-48QF2-32DP-8LA	AF9708 (ver 1.44 or later) AF9709 (ver 1.44 or later)
FPT-48P-M16	ROM2-48QF-32DP-8LA	

Enquiries

Sun Hayato Co. Ltd.: TEL 03-3986-0403 Ando Denki Co. Ltd.: TEL 044-549-7300

2. PROM Mode Memory Map



3. PROM Programming Procedure (When using an Ando EPROM programmer)

- 1) Set the EPROM programmer type code to 17209.
- 2) Load the program data into addresses 0000H to 3FFFH in the EPROM programmer.
- 3) Use the EPROM programmer to program to addresses C000H to FFFFH.

4. Programming Yield

Due to the nature of OTPROM memory, a program test to all bits on a blank OTPROM microcontroller cannot be performed at Fujitsu. For this reason, a programming yield of 100% cannot be assured at all times.

■ PROGRAMMING AND ERASING FLASH MEMORY ON THE MB89F969A

1. Flash Memory

The flash memory is located between 1000H and FFFFH in the CPU memory map and incorporates a flash memory interface circuit that allows read access and program access from the CPU to be performed in the same way as mask ROM. Programming and erasing flash memory is also performed via the flash memory interface circuit by executing instructions in the CPU. This enables the flash memory to be updated in place under the control of the CPU, providing an efficient method of updating program and data.

2. Flash Memory Features

- 60 K byte × 8-bit configuration (16 K + 8 K + 8 K + 28 K sectors)
- Automatic programming algorithm (Embedded algorithm*: Equivalent to MBM29LV200)
- Includes an erase pause and restart function
- Data polling and toggle bit for detection of program/erase completion
- Detection of program/erase completion via CPU interrupt
- Compatible with JEDEC-standard commands
- Sector Protection (sectors can be combined in any combination)
- No. of program/erase cycles: 10,000 (min.)

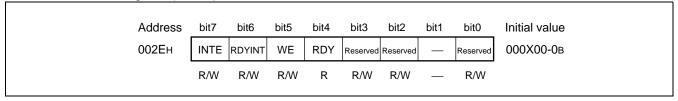
Embedded Algorithm is a trademark of Advanced Micro Devices.

3. Procedure for Programming and Erasing Flash Memory

Programming and reading flash memory cannot be performed at the same time. Accordingly, to program or erase flash memory, the program must first be copied from flash memory to RAM so that programming can be performed without program access from flash memory.

4. Flash Memory Register

Control status register (FMCS)



5. Sector Configuration

The table below shows the sector configuration of flash memory and lists the addresses of each sector for both during CPU access a flash memory programming.

Sector configuration of flash memory

Flash Memory	CPU Address	Programmer Address
16 K bytes	FFFFH to C000H	1FFFFн to 1C000н
8 K bytes	BFFF _H to A000 _H	1BFFFн to 1A000н
8 K bytes	9FFFн to 8000н	19FFFн to 18000н
28 K bytes	7FFFн to 1000н	17FFFн to 11000н

* : Programmer address

The programmer address is the address to be used instead of the CPU address when programming data from a parallel flash memory programmer. Use the programmer address on programming or erasing using a general-purpose parallel programmer.

6. ROM Programmer Adaptor and Recommended ROM Programmers

Package Name	Adaptor Part No.	Recommended Programmer Manufacturer and Model
	Sun Hayato Co. Ltd.	Ando Denki Co. Ltd.
FPT-64P-M09	FLASH-64QF2-32DP-8LF	AF9708 (ver 1.60 or later) AF9709 (ver 1.60 or later)

• Enquiries

Sun Hayato Co. Ltd. : TEL 03-3986-0403 Ando Denki Co. Ltd. : TEL 044-549-7300

■ PROGRAMMING A PIGGYBACK/EVALUATION EPROM

1. EPROM Type

MBM27C256A-20TVM

2. Programming Adaptor

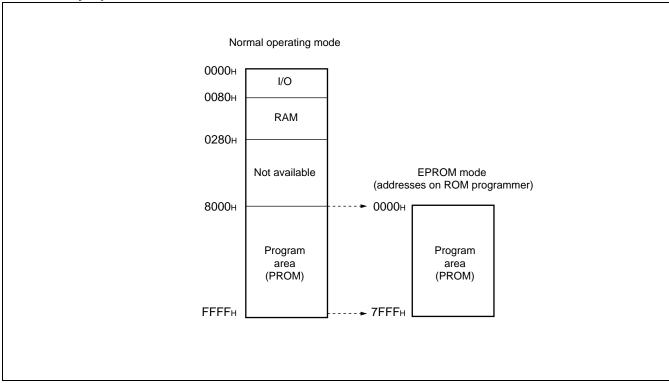
Use the following programming adaptor (made by Sun Hayato Co. Ltd.) to program the EPROM using a ROM programmer.

Programming adaptor

Package	Adaptor Socket Part No.
LCC-32 (Square)	ROM-32LC-28DP-S

Enquiries Sun Hayato Co. Ltd.: TEL03-3986-0403

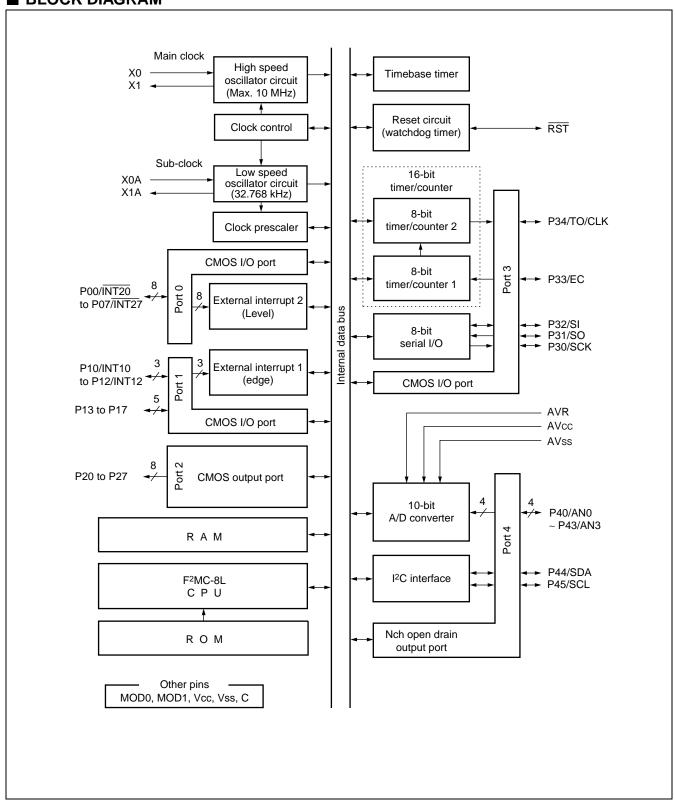
3. Memory Space



4. EPROM Programming Procedure

- (1) Setup the EPROM programmer to the MBM27C256A.
- (2) Load the program data into addresses 0000_H to 7FFF_H in the EPROM programmer.
- (3) Use the ROM programmer to program to addresses 0000H to 7FFFH.

■ BLOCK DIAGRAM



■ CPU CORE

1. Memory Space

(1) Structure of memory space

- I/O area (address : 0000н to 007Fн)
- Assign the control registers, data registers, and similar of the internal peripheral functions.
- As the I/O area is allocated as part of the memory space, it can be accessed in the same way as memory.
 Direct addressing also provides high speed access.

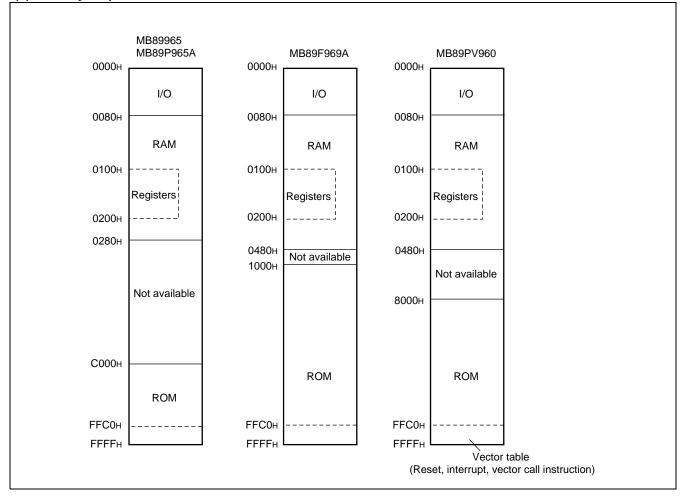
RAM area

- Static RAM is provided as an internal data area.
- The size of internal RAM differs between products.
- Addresses 80_H to FF_H provide high speed access using direct addressing.
- Addresses 100_H to 1FF_H are used as the general-purpose register area.
- The initial value of RAM after a reset is undefined.

ROM area

- ROM memory is provided as the internal program area.
- The size of internal ROM differs between products.
- Addresses FFC0_H to FFFF_H are used for the vector table and similar.

(2) Memory map



2. Registers

The MB89960 series provides two types of registers: dedicated registers in the CPU and general-purpose registers. The dedicated registers are as follows.

Program counter (PC) : A 16-bit register for indicating the instruction storage positions.

Accumulator (A) : A 16-bit register that provides temporary storage for arithmetic operations and

similar. Instructions that operate on 8-bit data use the lower byte.

Temporary accumulator (T) : A 16-bit register used for arithmetic operations with the accumulator. Instructions

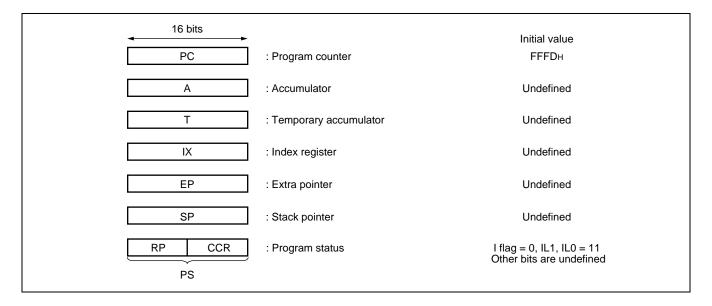
that operate on 8-bit data use the lower byte.

Index register (IX) : A 16-bit register used for index modification.

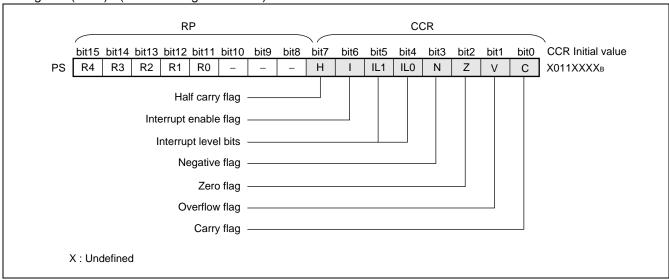
Extra pointer (EP) : A 16-bit pointer used for indicating a memory address .

Stack pointer (SP) : A 16-bit register used for indicating a stack area.

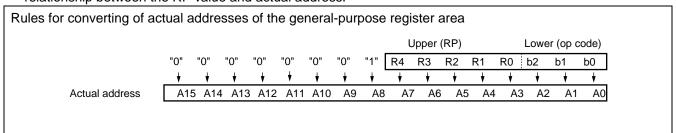
Program status (PS) : A 16-bit register used to store a register pointer and condition code.



The upper 8 bits of the PS contain the register bank pointer (RP) and the lower 8 bits contain the condition code register (CCR). (See the diagram below.)



The RP contains the address of the currently used register bank. The conversion diagram below shows the relationship between the RP value and actual address.



CCR contains bits that indicate the result of an arithmetic operation or information about transfer data and bits used to control CPU operation when an interrupt occurs.

H-flag : Set to "1" when a carry from bit 3 to bit 4 or a borrow from bit 4 to bit 3 occurs as a result of an arithmetic operation. Cleared to "0" otherwise. This flag is for decimal adjustment instructions and should be ignored for operations other than addition and subtraction.

I-flag : Interrupts are enabled when this flag is set to "1" and disabled when the flag is set to "0". Cleared to "0" by a reset.

IL1, 0 : Indicates the level of interrupts currently allowed. The CPU only processes interrupts with a request level higher than the value indicated by these bits.

IL1	IL0	Interrupt Level	Priority
0	0	1	High
0	1	l	<u>†</u>
1	0	2	
1	1	3	Low = No interrupt

N-flag : Set to "1" when the MSB of the result of an arithmetic operation is "1" and cleared to "0" when the

MSB is "0".

Z-flag : Set to "1" when the result of an arithmetic operation is zero. Cleared to "0" otherwise

V-flag : Set to "1" when a 2's complement overflow occurs as the result of an arithmetic operation. Cleared

to "0" if no 2's complement overflow occurs.

C-flag : Set to "1" when a carry from bit 7 or a borrow to bit 7 occurs as the result of an arithmetic opera-

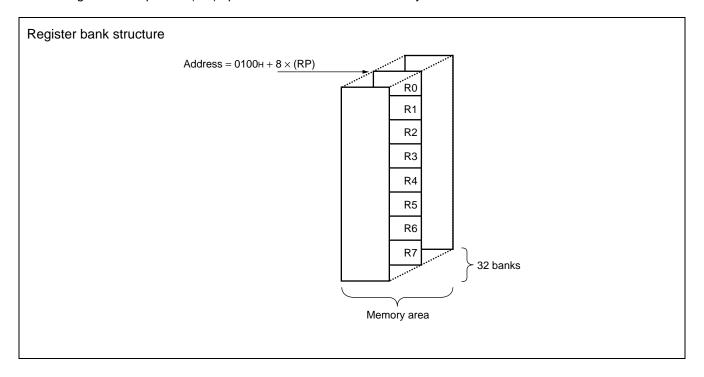
tion. Cleared to "0" otherwise. Set to the shift-out value in the case of a shift instruction.

The following general-purpose registers are provided:

General-purpose registers: 8-bit resisters for storing data

The general-purpose registers are 8-bit registers and are allocated in the register banks of the memory. Each bank contains 8 registers and all 32 banks can be used on MB89960 series microcontrollers.

The register bank pointer (RP) specifies the bank that is currently in use.



■ I/O MAP

Address	Abbreviation Register Name		Read/Write	Initial Value
00н	PDR0	Port 0 data register	R/W	XXXXXXXX
01н	DDR0	Port 0 direction register	W	0000000
02н	PDR1	Port 1 data register	R/W	XXXXXXXX
03н	DDR1	Port 1 direction register	W	0000000
04н	PDR2	Port 2 data register	R/W	0000000
05н		(11	1	1
06н		(Unused area)		
07н	SYCC	System clock control register	R/W	Х ММ1 0 Ов
08н	STBC	Standby control register	R/W	00010в
09н	WDTC	Watchdog control register	R/W	0XXXX _B
ОАн	TBTC	Timebase timer control register	R/W	00000в
0Вн	WPCR	Clock prescaler control register	R/W	00000в
0Сн	PDR3	Port 3 data register	R/W	XXXXXB
0Дн	DDR3	Port 3 direction register	R/W	000000в
0Ен	PDR4	Port 4 data register	R/W	111111в
0Fн	1	(Unused area)	l	T .
10н	IBSR	I ² C bus status register	R	00000000
11н	IBCR	I ² C bus control register	R/W	00011000в
12н	ICCR	I ² C clock control register	R/W	000XXXXXB
13н	IADR	I ² C address register	R/W	-XXXXXXXB
14н	IDAR	I ² C data register	R/W	XXXXXXXX
15н			1	1
16н		(Unused area)		
17н				
18н	T2CR	Timer 2 control register	R/W	Х0ХХХОв
19н	T1CR	Timer 1 control register	R/W	X000XXX0 _B
1Ан	T2DR	Timer 2 data register	R/W	XXXXXXXX
1Вн	T1DR	Timer 1 data register	R/W	XXXXXXXX
1Сн	SMR	Serial mode register	R/W	0000000
1Dн	SDR	Serial data register	R/W	XXXXXXXX
1Ен		(Harrison area)	- 1	1
1Fн		(Unused area)		
20н	ADC1	A/D control register 1	R/W	000000-0в
21н	ADC2	A/D control register 2	R/W	-0000001в
22н	ADDH	A/D data register H	R/W	XX _B

(Continued)

(
Address	Abbreviation	Register Name	Read/Write	Initial Value
23н	ADDL	A/D data register L	R/W	XXXXXXXXB
24н	EIC1	External interrupt 1 control register 1	R/W	0000000
25н	EIC2	External interrupt 1 control register 2	R/W	0000В
26н to 27н		(Unused area)		
28н	PURR1	Pull-up resistor register 1 (MB89965, P965A, and F969A only)	R/W	11111111
29н	PURR2	Pull-up resistor register 2 (MB89965, P965A, and F969A only)	R/W	11111111
2Ан	PURR3	Pull-up resistor register 3 (MB89965, P965A, nd F969A only)	R/W	XXX1 1 1 1 1 _B
2Вн	PURR4	Pull-up resistor register 4 (MB89965, P965A, and F969A only)	R/W	XXXX1 1 1 1 _B
2Cн to 31н		(Unused area)		
32н	EIE2	External interrupt 2 control register	R/W	0000000B
33н	EIF2	External interrupt 2 flag register	R/W	Ов
34н to 7Вн		(Unused area)		
7Сн	ILR1	Interrupt level setting register 1	W	11111111
7Dн	ILR2	Interrupt level setting register 2	W	11111111
7Ен	ILR3	Interrupt level setting register 3	W	11111111
7 Fн	ITR	Interrupt test register	Not available	XXXXXX0 0 _B

• Read/write notation

R/W : Reading and writing available

R : Read-only W : Write-only

• Initial value notation

0 : Initial value of bit is "0".1 : Initial value of bit is "1".

X : Initial value of bit is undefined.

M : Initial value of bit is specified by mask option.

- : Bit is not used.

Note: Do not use the "unused areas".

■ ELECTRICAL CHARACTERISTICS

1. Absolute Maximum Ratings

(AVss = Vss = 0.0 V)

Parameter	Symbol	Rat	ting	Unit	Remarks	
Farameter	Syllibol	Min.	Max.	Onne	Remarks	
Power supply voltage	Vcc AVcc	Vss - 0.3	Vss + 6.0	V	*	
	AVR	Vss - 0.3	Vss + 6.0			
Input voltage	Vı	Vss - 0.3	Vcc + 0.3	V	Pins other than P44 and P55	
Input voltage	VI	Vss - 0.3	Vss + 6.0]	Pins P44 and P45	
Output voltage	Vo	Vss - 0.3	Vcc + 0.3	V	Pins other than P44 and P55	
Output voltage	Vo	Vss - 0.3	Vss + 6.0]	Pins P44 and P45	
"L" level maximum output current	loL	_	15	mA		
"L" level average output current	lolav	_	4	mA	Average value (operating current × operating ratio)	
"L" level total maximum output current	ΣΙοι	_	100	mA		
"L" level total average output current	ΣΙοιαν	_	40	mA	Average value (operating current × operating ratio)	
"H" level maximum output current	Іон	_	-15	mA		
"H" level average output current	Іонач	_	-4	mA	Average value (operating current × operating ratio)	
"H" level total maximum output current	ΣІон	_	-50	mA		
"H" level total average output current	ΣΙοнαν	_	-20	mA	Average value (operating current × operating ratio)	
Dawaraanawantian	Б	_	300	\\/		
Power consumption	P _D	_	450	mW	MB89F969A only	
Operating temperature	TA	-40	+85	°C		
Storage temperature	Tstg	-55	+150	°C		

^{* :} Set AVcc to the same potential as Vcc. Also ensure that AVcc does not exceed Vcc at power on.

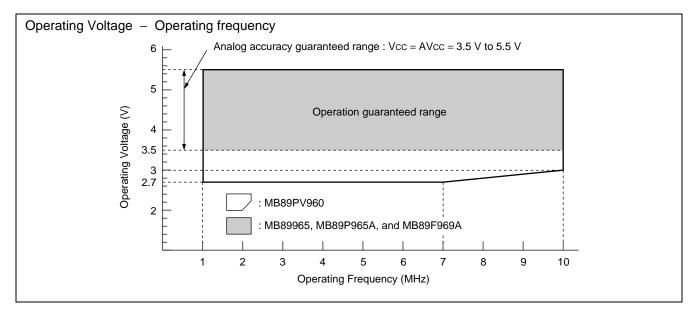
WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

2. Recommended Operating Conditions

(AVss = Vss = 0.0 V)

Parameter	Symbol	Va	lue	Unit	Remarks
raiailletei	Зуппоот	Min.	Max.	Ullit	Remarks
	Vcc AVcc	3.5*	5.5*	V	Normal operation guaranteed range (MB89965/P965A/F969A)
		3.0	5.5	V	To maintain RAM state in stop mode (MB89965/P965A/F969A)
Power supply voltage		2.7*	5.5*	V	Normal operation guaranteed range (MB89PV960)
		1.5	5.5	V	To maintain RAM state in stop mode (MB89PV960)
	AVR	3.5	AVcc	V	
Operating temperature	TA	-40	+85	°C	

^{*:} Differs depending on the operating frequency and analog guaranteed range. See the figure below and "5. Electrical Characteristics for the A/D Converter".



The figure above shows the frequency of the external oscillator when the instruction cycle setting is 4/Fc. As the operating voltage depends on the instruction cycle, change to the new instruction cycle value if using the gear function to change the operating speed.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

3. DC Characteristics

(AVcc = Vcc = 5.0 V, AVss = Vss = 0.0 V, T_{A} = -40 °C to +85 °C)

Parameter	Sym-	Pin Name	Condition		Value	Unit	Remarks	
Parameter	bol	Pili Naille	Condition	Min.	Тур.	Max.	Ullit	Remarks
"H" level input	Vıн	P00 to P07, P10 to P17, P30 to P34	_	0.7 Vcc	_	Vcc + 0.3	V	
	V _{IHS}	RST, INT20 to INT27, INT10 to INT12, SI, SCK, EC, TEST		0.8 Vcc	_	Vcc + 0.3	V	
voltage	Vінм	MOD0/1/2	_	Vcc - 0.3	_	Vcc + 0.3	V	MOD pin input
	VIHSMB	SCL, SDA		Vss + 1.4	_	Vss + 5.5	V	When SMB selected
	V _{IHI2C}	JOCE, SDA	_	0.7 Vcc	_	Vss + 5.5	V	When I ² C selected
	Vıl	P00 to P07, P10 to P17, P30 to P34	_	Vss - 0.3	_	0.3 Vcc	V	
"L" level input	Vils	RST, INT20 to INT27, INT10 to INT12, SI, SCK, EC, TEST	_	Vss - 0.3		0.2 Vcc	V	
voltage	VILM	MOD0/1/2	_	Vss - 0.3	_	Vss + 0.3	V	MOD pin input
	VILSMB	SCL, SDA		Vss - 0.3	_	Vss + 0.6	V	When SMB selected
	V _{ILI2C}	JOCE, SDA	_	Vss - 0.3	_	0.3 Vcc	V	When I ² C selected
Voltage applied to open drain output pins	V _D	P40 to P45	_	Vss - 0.3	_	Vcc + 0.3	V	
"H" level output voltage	Vон	P00 to P07, P10 to P17, P20 to P27, P30 to P34	Iон = -2.0 mA	4.0	_	_	V	
"L" level output voltage	Vol	P00 to P07, P10 to P17, P20 to P27, P30 to P34, P40 to P45, RST	lo _L = 4.0 mA	_	_	0.4	V	

(AVcc = Vcc = 5.0 V, AVss = Vss = 0.0 V, T_A = -40 °C to +85 °C)

Parameter	Sym-	Pin Name	Condition		Value		Unit	Remarks
Parameter	bol	Pin Name	Condition	Min.	Тур.	Max.	Unit	Remarks
Input leak current	lu	P00 to P07, P10 to P17, P20 to P27, P30 to P34, P40 to P45	0 V < Vı < Vcc	-5	_	+5	μΑ	Without pull- up resistor option
		MOD0/1/2, TEST		-10		+10		
Open-drain output leak current	ILIOD	P40 to P45	0 V < V1 < Vss + 5.5 V	_	_	+5	μА	
Pull-up resistance	Rpull	P00 to P07, P10 to P17, P20 to P27, P30 to P34, P40 to P45, RST	Vı = 0.0 V	25	50	100	Ω	With pull-up resistor option
			E 400 MI		10	20		MB89PV960
	Icc1		Fch = 10.0 MHz tinst*2 = 0.4 µs main run mode		4	7	mA	MB89965 MB89P965A
			main run mode	_	5	8		MB89F969A
		Vcc	F _{CH} = 10.0 MHz	_	3	8		MB89PV960
Power supply current*1	Icc2	(when using an external clock)	tinst*2 = 6.4 μ s main run mode	_	1	3	mA	MB89965 MB89P965A MB89F969A
]	F _{CH} = 10.0 MHz	_	3	8		MB89PV960
	Iccs1		$t_{\text{INST}}^{*2} = 0.4 \mu\text{s}$ main sleep mode	_	2	4	mA	MB89965 MB89P965A MB89F969A

(Continued)

(AVcc = Vcc = 5.0 V, AVss = Vss = 0.0 V, $T_A = -40$ °C to +85 °C)

Parameter	Sym-	Pin Name	Condition		Value		Unit	Remarks
rarameter	bol	Fill Name	Condition	Min.	Тур.	Max.	Ollic	Remarks
	Iccs2		$\begin{aligned} F_{\text{CH}} &= 10.0 \text{ MHz} \\ t_{\text{INST}}^{*2} &= 6.4 \mu\text{s} \\ \text{main sleep mode} \end{aligned}$		1	3	mA	
				_	70	150		MB89PV960
Power supply	Icci		Fcн = 32.768 kHz	_	20	100	μΑ	MB89965
	ICCL	Vcc	sub run mode		0.3	1	mA	MB89P965A MB89F969A
	Iccls	(when using an external	FcH = 32.768 kHz sub sleep mode		10	50	μΑ	
	Icct clock)	FcH = 32.768 kHz • clock mode, main stop mode	_	5	15	μΑ		
				_	1	10		MB89PV960
	I CCH	T _A = +25 °C • sub stop mode	_	5	10	μΑ	MB89965 MB89P965A MB89F969A	
Input capacitance	Cin	Except AVcc, AVss, Vcc, and AVss	f = 1 MHz	_	10	_	pF	

^{*1 :} The power supply current values are for an external clock.

^{*2:} See " (4) Instruction Cycle" in "4. AC Characteristics".

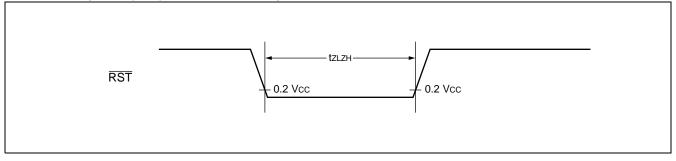
4. AC Characteristics

(1) Reset Timing

$$(V_{CC} = 5.0 \text{ V}, \text{ AVss} = \text{Vss} = 0.0 \text{ V}, \text{ Ta} = -40 ^{\circ}\text{C to} +85 ^{\circ}\text{C})$$

Parameter	Symbol	Condition	Value		Unit	Remarks	
i arameter	Symbol	Condition	Min.	Max.	Offic	Remarks	
RST "L" pulse width	t zlzh	_	48 thcyL*	_	ns		

*: they is the period (1/Fc) of the oscillation input to X0.

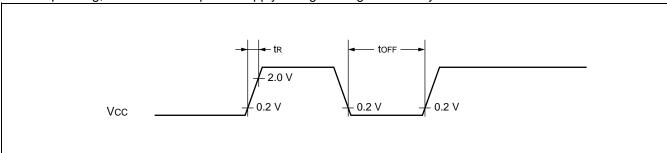


(2) Power-On Reset

(AVss = Vss = 0.0 V,
$$T_A = -40 \, ^{\circ}\text{C}$$
 to +85 $^{\circ}\text{C}$)

Parameter	Symbol	Condition	Va	lue	Unit	Remarks
Farameter	Syllibol	Condition	Min.	Max.	Onit	Remarks
Power supply rising time	t R	_	0.5	50	ms	
Power supply cutoff time	t off		1	_	ns	For repeated operation

Note: Ensure that the power supply rising time is less than the selected oscillation stabilization delay time. For example, if the main clock frequency $F_C = 10$ MHz and $2^{14}/F_C$ is selected as the oscillation stabilization delay time, the resulting oscillation stabilization delay time is 1.6 ms. As rapid changes in the power supply voltage may cause a power-on reset, if you need to change the power supply voltage while the device is operating, ensure that the power supply voltage changes smoothly.

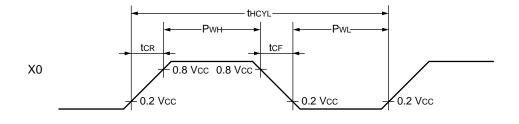


(3) Clock Timings

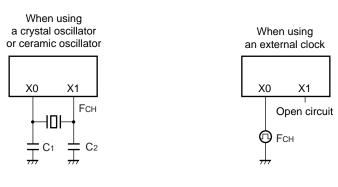
(AVss = Vss = 0.0 V,
$$T_A = -40 \, ^{\circ}\text{C}$$
 to +85 $^{\circ}\text{C}$)

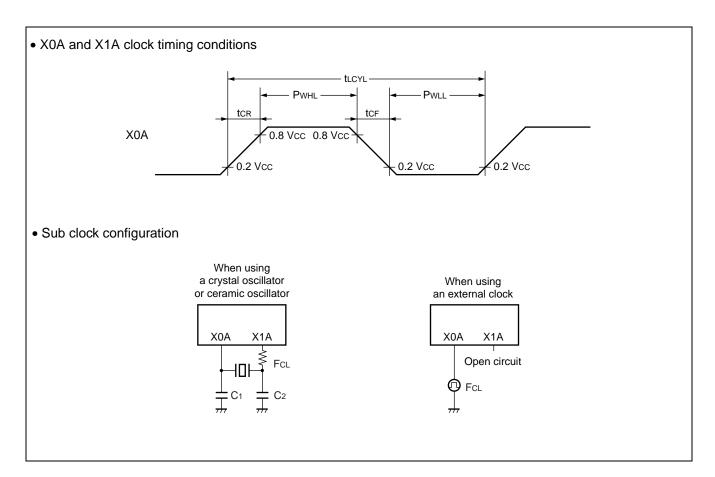
	1		1				
Parameter	Symbol	Pin Name		Value	Unit	Remarks	
raiailletei	Syllibol	riii Naiile	Min.	Тур.	Max.	Oilit	Nemarks
Clock frequency	Fсн	X0, X1	1	_	10	MHz	Main clock
Clock frequency	FcL	X0A, X1A	_	32.768	_	kHz	Sub clock
Clask avalatima	t HCYL	X0, X1	100	_	1000	ns	Main clock
Clock cycle time	t LCYL	X0A, X1A	_	30.5	_	μs	Sub clock
Input clock pulse width	Pwh PwL	X0	20	_	_	ns	External clock
impat clock puise width	P _{WHL} P _{WLL}	X0A	_	15.2	_	μs	External clock
Input clock rising/falling time	tcr tcr	X0		_	10	ns	External clock

• X0 and X1 clock timing and input conditions



• Clock configurations





(4) Instruction Cycle

(AVss = Vss = 0.0 V,
$$T_A = -40 \, ^{\circ}\text{C}$$
 to +85 $^{\circ}\text{C}$)

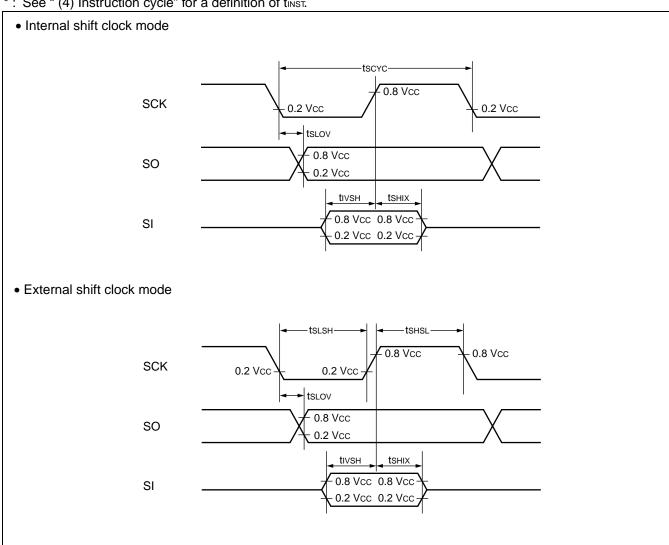
Parameter	Symbol	Value	Unit	Remarks
Instruction cycle (Minimum instruction execution time)	t inst	4/Fcн, 8/Fcн, 16/Fcн, 64/Fcн t		$\begin{aligned} &\text{FcH} = 10 \text{ MHz (4/FcH) operation} \\ &\text{time} \\ &\text{tinst} = 0.4 \mu\text{s} \end{aligned}$
		2/FcL	- μs	$\begin{aligned} & \text{FcL} = 32.768 \text{ kHz operation} \\ & \text{time} \\ & \text{tinst} = 61.036 \mu\text{s} \end{aligned}$

(5) Serial I/O Timings

 $(V_{CC} = 5.0 \text{ V}, \text{ AV}_{SS} = \text{V}_{SS} = 0.0 \text{ V}, \text{ T}_{A} = -40 \,^{\circ}\text{C} \text{ to } +85 \,^{\circ}\text{C})$

Parameter	Sym- bol	Pin Name	Condition	Value		Unit	Remarks
				Min.	Max.	Onn	Nemarks
Serial clock cycle time	tscyc	SCK	Internal clock operation	2 tinst*	_	μs	
$SCK \downarrow \to SO$ delay time	t sLOV	SCK, SO		-200	200	ns	
Valid SI → SCK ↑	t ıvsh	SCK, SI		200	_	ns	
$SCK \uparrow \rightarrow valid SI hold time$	t sHIX	SCK, SI		200		ns	
Serial clock "H" pulse width	t shsl	SCK	External clock operation	tinst*	_	μs	
Serial clock "L" pulse width	t slsh	SCK		tinst*	_	μs	
$SCK \downarrow \to SO$ delay time	t sLOV	SCK, SO		0	200	ns	
Valid SI → SCK	t ıvsh	SCK, SI		200	_	μs	
$SCK \uparrow \rightarrow valid SI hold time$	t sнıx	SCK, SI		200		μs	

*: See " (4) Instruction cycle" for a definition of tinst.

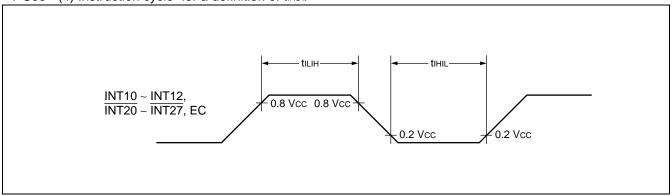


(6) Peripheral Input Timings

 $(Vcc = 5.0 \text{ V}, \text{ AVss} = \text{Vss} = 0.0 \text{ V}, \text{ T}_{A} = -40 \,^{\circ}\text{C to} +85 \,^{\circ}\text{C})$

Parameter	Symbol	Pin Name	Va	lue	Unit	Remarks
i didilietei		i iii Naiiie	Min.	Max.		
Peripheral input "H" pulse width	tıшн	INT10 to INT12,	2 tinst*	_	μs	
Peripheral input "L" pulse width	tıнı∟	INT20 to INT27, EC	2 tinst*		μs	

*: See " (4) Instruction cycle" for a definition of tinst.



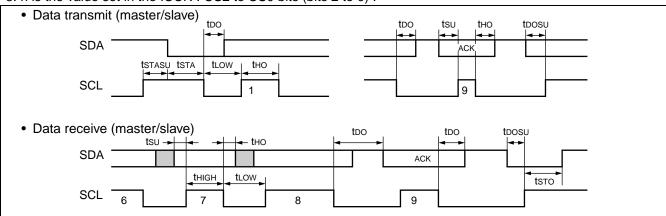
(7) I²C Timings

(Vcc = 5.0 V, AVss = Vss = 0.0 V,
$$T_A = -40$$
 °C to +85 °C)

Parameter	Sym bol	Pin	Value			Remarks
Faranteter			Min.	Max.	Unit	neiliai ks
Start condition output	t sta	SCL SDA	$1/4t_{\text{INST}}^{*1} \times m^* \times n^{*3} - 20$	$1/4$ tinst*1 \times m*2 \times n*3 + 20	ns	Master mode
Stop condition output	t sто	SCL SDA	$1/4t_{INST}^{*1} \times (m^{*2} \times n^{*3} + 8) - 20$	$1/4t_{INST}^{*1} \times (m^{*2} \times n^{*3} + 8) + 20$	ns	Master mode
Start condition detect	t sta	SCL SDA	$1/4t$ INST $^{*1} \times 6 + 40$	_	ns	
Stop condition detect	t sto	SCL SDA	$1/4$ tinst*1 \times 6 + 40	_	ns	
Restart condition output	t stasu	SCL SDA	$1/4t_{INST}^{*1} \times (m^{*2} \times n^{*3} + 8) - 20$	$1/4t_{INST}^{*1} \times (m^{*2} \times n^{*3} + 8) + 20$	ns	Master mode
Restart condition detect	t stasu	SCL SDA	$1/4t_{\text{INST}}^{*1} \times 4+40$	_	ns	
SCL output "L" width	t LOW	SCL	$1/4t_{\text{INST}}^{*1} \times m^{*2} \times n^{*3} - 20$	$1/4t_{INST}^{*1} \times m^{*2} \times n^{*3} + 20$	ns	Master mode
SCL output "H" width	t HIGH	SCL	$1/4t_{INST}^{*1} \times (m^{*2} \times n^{*3} + 8) \\ -20$	$1/4t_{INST}^{*1} \times (m^{*2} \times n^{*3} + 8) + 20$	ns	Master mode
SDA output delay	t DO	SDA	$1/4t_{\text{INST}}^{*1} \times 4 - 20$	$1/4t_{\text{INST}}^{*1} \times 4 + 20$	ns	
SDA output setup time after interrupt	toosu	SDA	$1/4$ tinst $^{*1} \times 4 - 20$	_	ns	
SCL input "L" pulse width	t LOW	SCL	$1/4t$ INST $^{*1} \times 6 + 40$	_	ns	
SCL input "H" pulse width	t HIGH	SCL	$1/4t_{\text{INST}}^{*1} \times 2 + 40$	_	ns	
SDA input setup time	t su	SDA	40	_	ns	
SDA hold time	t но	SDA	0	_	ns	

^{*1:} See " (4) Instruction cycle" for a definition of tinst.

^{*3:} n is the value set in the ICCR: CS2 to CS0 bits (bits 2 to 0).



^{*2:} m is the value set in the ICCR: CS4 and CS3 bits (bits 4 to 3).

5. Electrical Characteristics for the A/D Converter

(AVcc = 3.5 V to 5.5 V, AVss = Vss = 0.0 V, T_{A} = $-40~^{\circ}C$ to +85 $^{\circ}C)$

Parameter	Sym bol	Pin	Condition	Value			Unit	Remarks
Parameter				Min.	Тур.	Max.	Unit	Remarks
Resolution			_	_	_	10	bit	
Total error				-5.0	_	+5.0	LSB	
Non-linearity error] —			-2.5	_	+2.5	LSB	
Differential linearity error		_	AVR = Avcc	-1.9	_	+1.9	LSB	
Zero transition voltage	Vот			AVR – 3.5 LSB	AVR + 0.5 LSB	AVR + 4.5 LSB	mV	
Full-scale transition voltage	V _{FST}	_		Vcc – 6.5 LSB	Vcc – 1.5 LSB	Vcc + 1.5 LSB	mV	
Variation between channels	_			_	_	4	LSB	
A/D mode conversion time*2	_		_	_	60 tinst*1	_	μs	MB89965 MB89P965A MB89F969A
				_	38 tinst*1	_	μs	MB89PV960
A/D sampling time				_	16 tinst*1	_	μs	
Analog input current	Iain	AN0				10	μΑ	
Analog input voltage range	Vain	to AN3		AVss		AVR	V	
	lΑ	Avcc	A/D operation	_	1.5	3	mA	
Power supply current	Іан		$T_A = +25 ^{\circ}C$ A/D stop	_	1	5	μΑ	
Reference voltage	_		_	AVss + 3.5	_	AVcc	V	
Reference voltage	lπ	AVR	A/D operation	_	400	_	μΑ	
supply current	I _{RH}		A/D stop			5	μΑ	

^{*1 :} See " (4) Instruction cycle" for a definition of tinst.

^{*2 :} Includes sampling time.

6. A/D Converter Glossary

Resolution

The change in analog voltage that can be recognized by the A/D converter.

• Linearity error (unit : LSB)

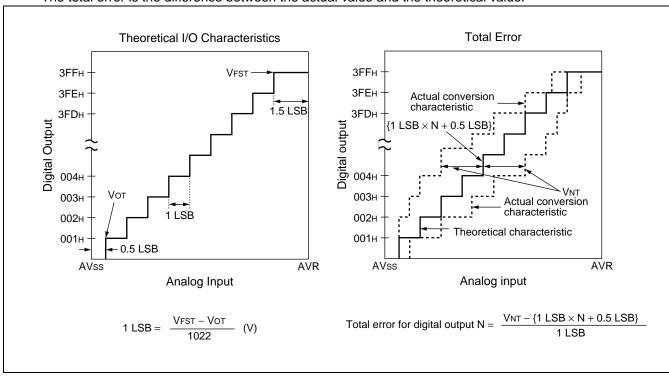
The deviation between the actual conversion characteristics and the line linking the zero transition point ("00 $0000\ 0000\ B$ " \longleftrightarrow "00 $0000\ 0001\ B$ ") and the full scale transition point ("11 1111 1110B" \longleftrightarrow "11 1111 1111B").

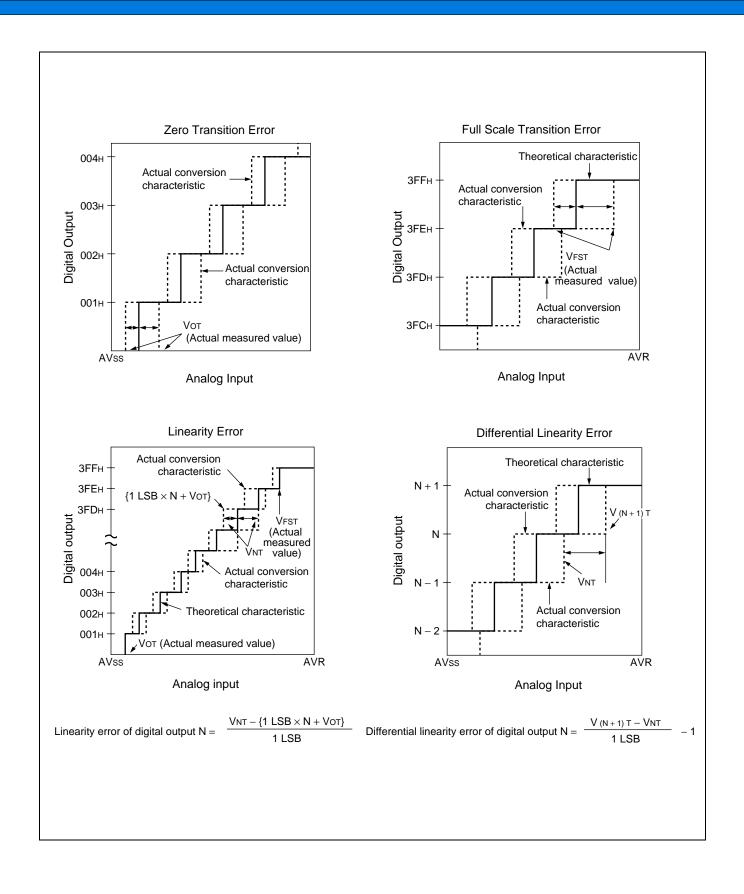
• Differential linearity error (unit : LSB)

The variation from the ideal input voltage required to change the output code by 1 LSB.

• Total error (unit : LSB)

The total error is the difference between the actual value and the theoretical value.

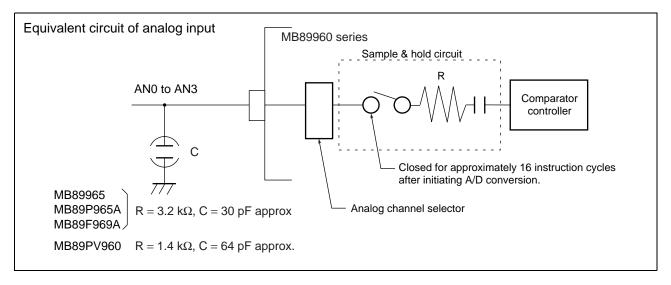




7. Notes for A/D Conversion

Analog input pins and input impedance

The A/D converter incorporates a sample & hold circuit as shown below. When an A/D conversion starts, the voltage at the analog input pin is captured by the sample & hold capacitor for a period of 16 instruction cycles. Accordingly, if the output impedance of the external circuit connected to the analog input is high, the analog input voltage may not stabilize within the period of the analog input sampling time. Therefore, ensure that the output impedance of the external circuit is sufficiently low (10 k Ω or less) . If it is not possible to reduce the output impedance of the external circuit, connecting an external capacitor of approximately 0.1 μ F is recommended.



• Error

The relative error increases as |AVR - AVss| becomes smaller.

8. Electrical Characteristics of Flash Memory

• Programming and erasing characteristics

Parameter		Sym bol	Pin Name	Condition	Value		Unit	Domorko		
Parameter					Min.	Тур.	Max.	Unit	Remarks	
Power supply current*1			IFWE	Vcc	Vcc = 5.0 V	_	_	40	mΑ	
Sector erasing time	Fixed time per sector regardless of size	Successful completion time				_	1	15	S	
		Unsuccess- ful comple- tion time			_	_	_	*2	_	
Programming time	per byte	Successful completion time		_	_	_	8	3600	μs	
		Unsuccess- ful comple- tion time				_	650	3600	μs	

^{*1 :} Automatic algorithm executing

^{*2 :} If a fault occurs during sector erasing, detection via DQ_5 may not be available ($DQ_5 = 1$ may not occur) . Accordingly, a fault must be assumed after 15 s, even if DQ_5 does not go to "1".

■ MASK OPTIONS

NO	Part No.	MB89965	MB89P965A/ MB89F969A	MB89PV960	
NO	Specifying procedure	Specify when ordering mask	Not available	Not available	
1	Initial value* selection for main clock oscillation stabilization delay time (FcH = 10 MHz) • 01 : 2 ¹² /FcH (0.4 ms approx.) • 10 : 2 ¹⁶ /FcH (6.6 ms approx.) • 11 : 2 ¹⁸ /FcH (26.2 ms approx.)	Selectable	2 ¹⁸ /Fсн (26.2 ms approx.)	2 ¹⁸ /Fcн (26.2 ms approx.)	

Fсн : Frequency of main clock oscillation

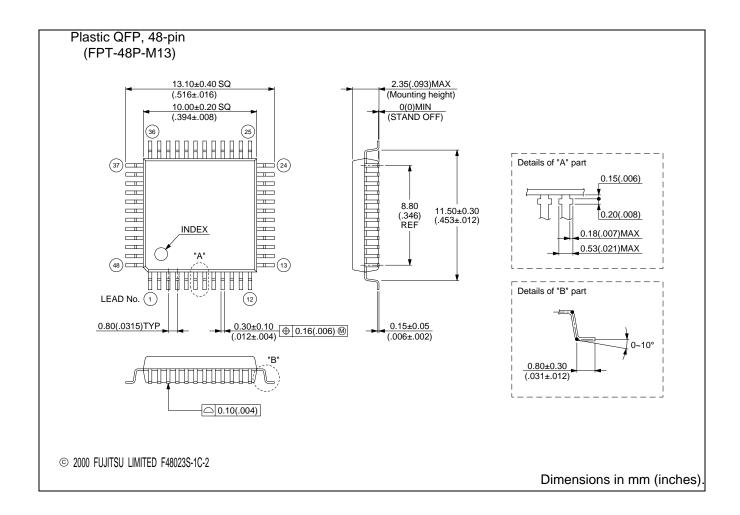
■ ORDERING INFOMATION

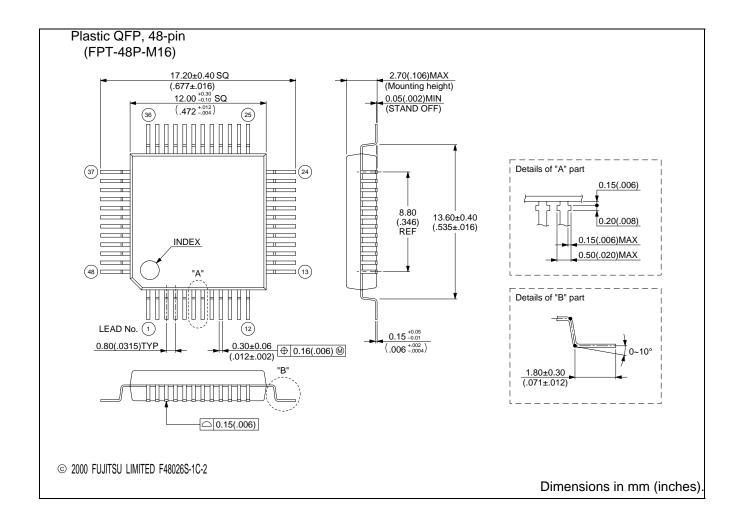
Part Number	Package	Remarks
MB89965PFV1 MB89P965APFV1 MB89965CPFV1	Plastic LQFP, 48-pin (FPT-48P-M05)	The MB89965PFV1 does not have an I ² C function.
MB89965PFM MB89P965APFM MB89965CPFM	Plastic QFP, 48-pin (FPT-48P-M13)	The MB89965PFM does not have an I ² C function.
MB89965PF MB89P965APF MB89965CPF	Plastic QFP, 48-pin (FPT-48P-M16)	The MB89965PF does not have an I ² C function.
MB89F969APFM	Plastic LQFP, 64-pin (FPT-64P-M09)	
MB89PV960CF	Ceramic MQFP, 48-pin (MQP-48C-P01)	

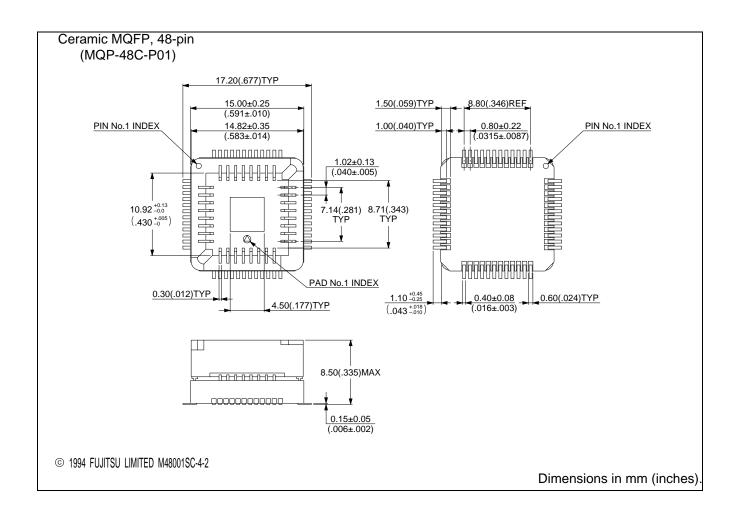
^{*:} This specifies the initial value after a reset of the oscillation stabilization delay time setting bits in the system clock control register (SYCC: WT1, WT0)

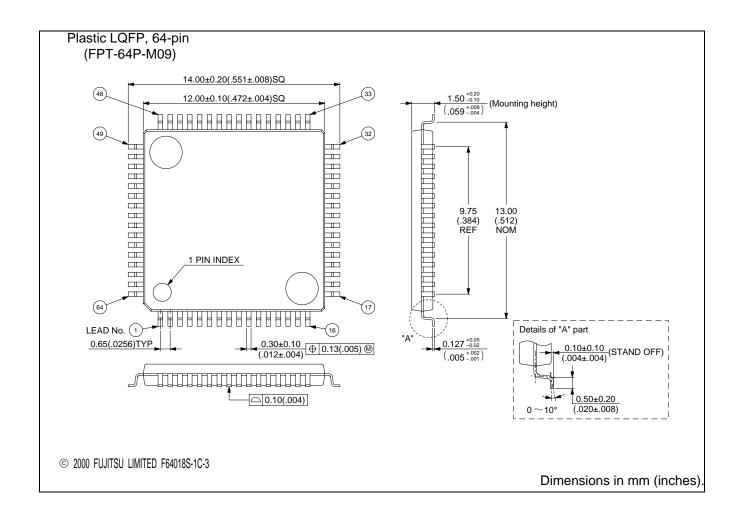
■ PACKAGE DIMENSIONS

(These package dimensions are provisional. Please obtain the actual dimensions of the final product separately.) Plastic LQFP, 48-pin Note: The pin width and thickness includes plating. (FPT-48P-M05) 9.00±0.20(.354±.008)SQ 0.145±0.055 (.006±.002) 7.00±0.10(.276±.004)SQ (25) (37) ___(24) Details of "A" part 0.08(.003) (.059 +.008) (Mounting height) INDEX (48) == **⊥**□(13) 0.10±0.10 (.004±.004) (Stand off) 0°~8° LEAD No. 1 (12) 0.50(.020) 0.25(.010) 0.50±0.20 (.020±.008) 0.60±0.15 (.024±.006) © 2000 FUJITSU LIMITED F48013S-c-4-8 Dimensions in mm (inches)









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